

Advanced pretreatment

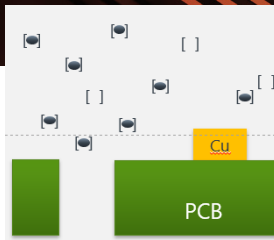
Tailored solutions for every copper condition



Electronics

Final finishing technology

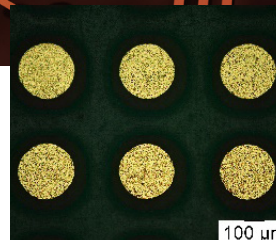
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ProActive PDX

Alkaline Cleaner

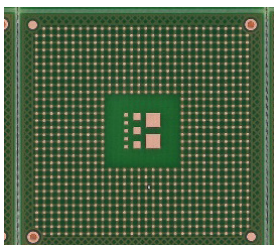
The mild, TU-free cleaner for Pd-removal and organic contaminants



ProSelect CT (Plus)

Alkaline Cleaner

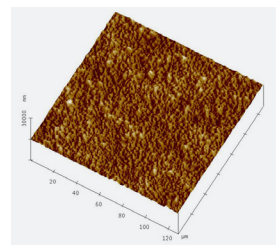
The mild cleaner for removal of organic residues



ProSelect S8

Acidic Cleaner

For an enhanced cleaning and wetting performance at any feature size



Coppertreat 800

Polishing Etch

The copper leveling etch for a smooth copper surface

Clean and smooth

Advanced pretreatment products improve copper cleanliness and homogeneity before the final finish step. Better copper cleanliness might effectively prevent defects such as discoloration and excessive plating. Our solutions combine lower copper roughness and improved Pd removal from the PTH process, such as cost-saving activation through lower precious metal concentration.

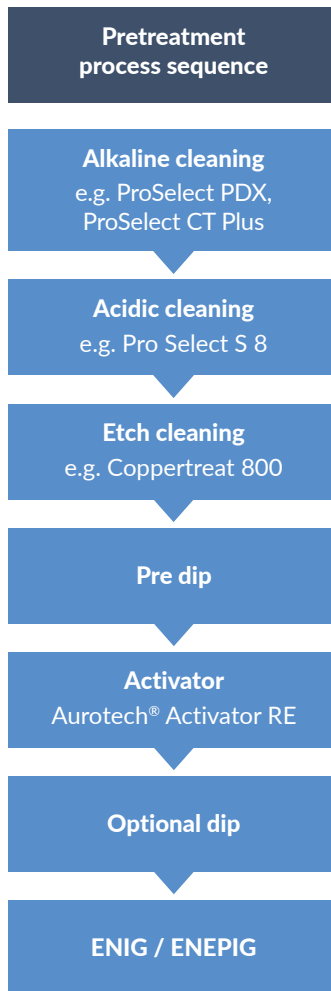


Aurotech ACT RE

Dense Activator

The cost-effective activator with homogeneous Pd seeding at reduced Pd concentration

New cleaner, microetch, and activator solution for ENIG and ENEPIG



ProActive PDX

- Mild, alkaline cleaner as Pd remover and passivator for ENIG and ENEPIG plating
- Improves excessive nickel plating and plating on base material by removing metallic residues
- Complexing agents complex the Pd at the given pH
- Complexed Pd is easy to be rinsed off
- Free of Thiourea

ProSelect CT (Plus)

- Medium alkaline cleaner for highly contaminated PCB's to remove grease, oil, and solder resist (SR) residues
- Prevents discoloration in ENIG plating process caused by leach out components from base material and solder resist
- Additive for enhanced SR removal available in "Plus" version

ProSelect S8

- Acidic cleaner with improved cleaning performance
- Improved, rapid surface wetting and cleaning capabilities through new surfactants and more
- Surfactants are biodegradable according to EU legislation and exhibit high thermal stability
- Free of NPE (nonylphenol ethoxylates) and PFOS (perfluorooctance sulfonates)

Coppertreat Series

- Copper Micro Etch system with polishing properties
- To process ENIG/ENEPIG independent from the incoming copper quality
- Mild etch rate of 0.5 – 1.2 $\mu\text{m}/\text{min}$ for a smooth and flat copper surface
- Oxidation prevention
- Fully analyzable, drop in solution
- Applicable in vertical and horizontal systems
- Suitable in dip, flood, or spray

Aurotech® Activator RE

- Reduced Pd-concentration in activator solution (20 mg/l)
- Reduced process costs for ENIG
- Reduced risk for excessive plating
- Surface enhancement facilitates more uniform Pd seeding

